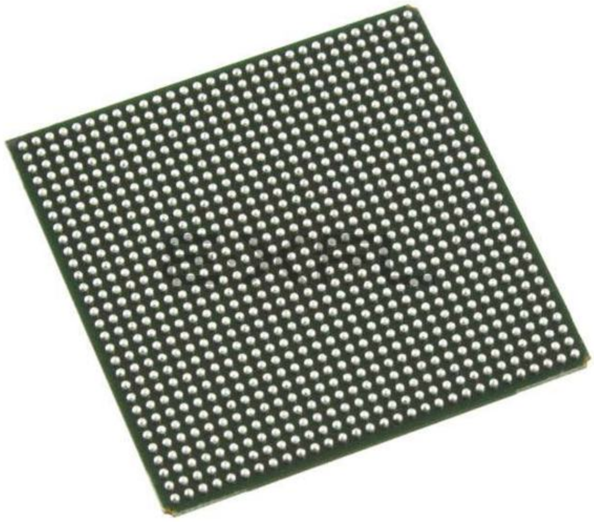
Lattice Semiconductor Corporation - LFE2M100E-6F900C Datasheet



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Understanding Embedded - FPGAs (Field Programmable Gate Array)

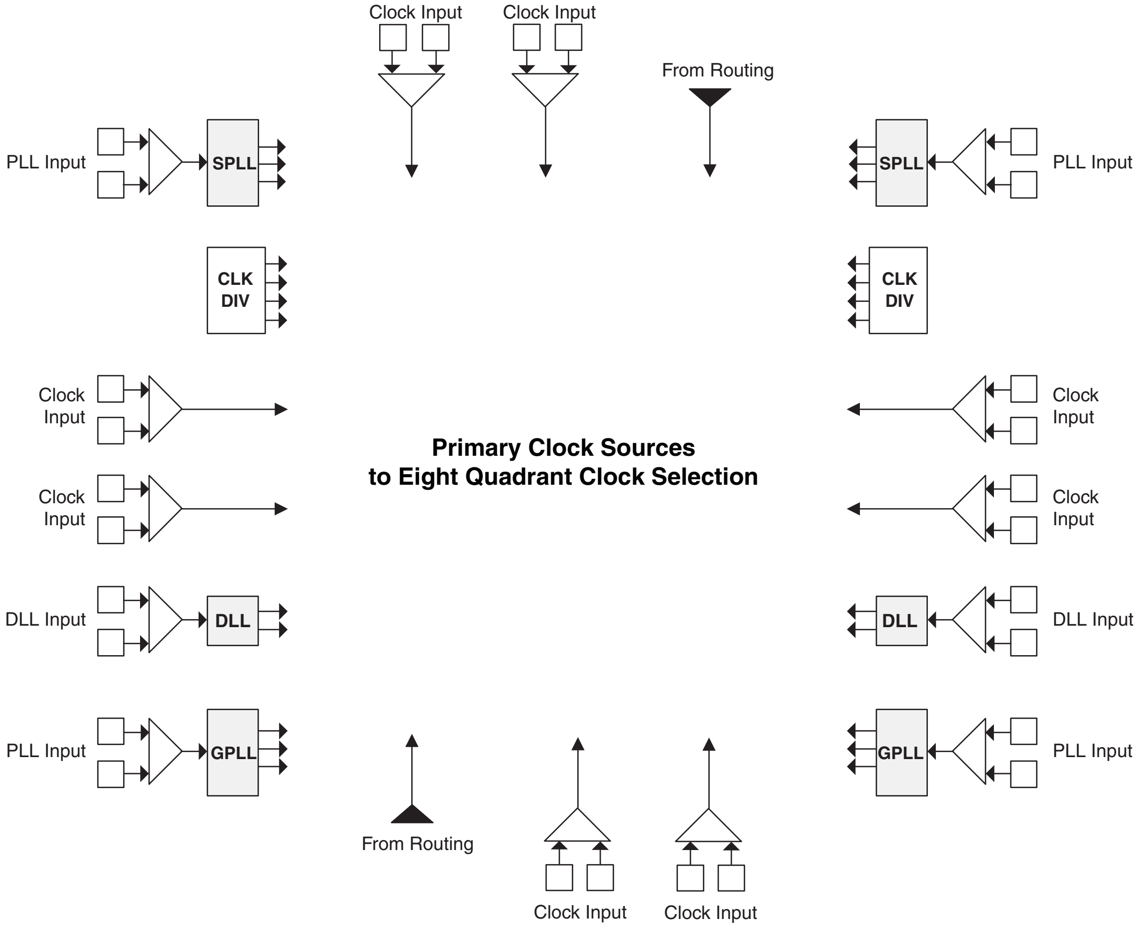
Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

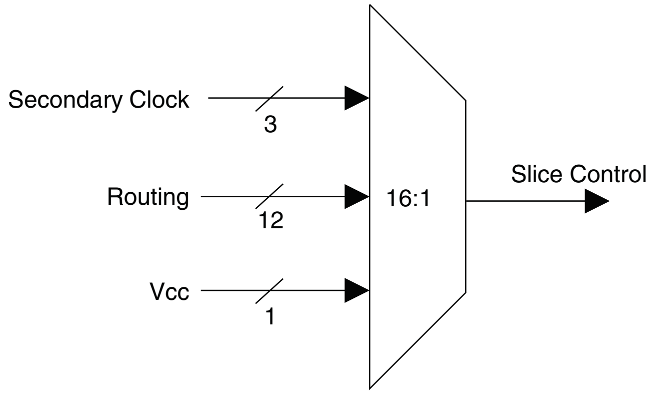
Details	
Product Status	Obsolete
Number of LABs/CLBs	11875
Number of Logic Elements/Cells	95000
Total RAM Bits	5435392
Number of I/O	416
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	900-BBGA
Supplier Device Package	900-FPBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2m100e-6f900c

Figure 2-10. Primary Clock Sources for ECP2-50



Note: This diagram shows sources for the ECP2-50 device. Smaller LatticeECP2 devices have fewer SPLLs. All LatticeECP2M devices have six SPLLs.

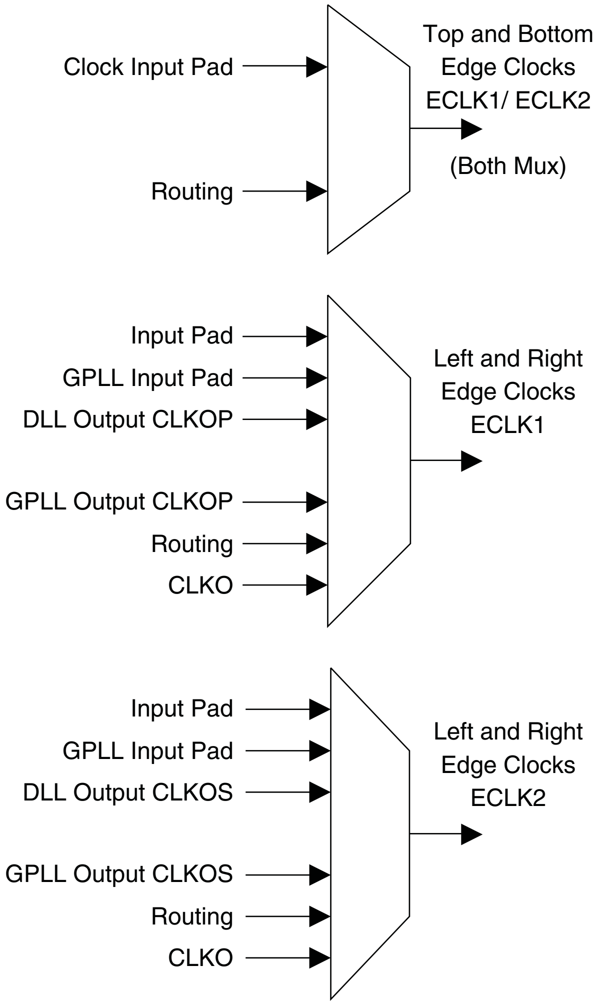
Figure 2-18. Slice0 through Slice2 Control Selection



Edge Clock Routing

LatticeECP2/M devices have a number of high-speed edge clocks that are intended for use with the PIOs in the implementation of high-speed interfaces. There are eight edge clocks per device: two edge clocks per edge. Different PLL and DLL outputs are routed to the two muxes on the left and right sides of the device. In addition, the CLKO signal (generated from the DLLDELA block) is routed to all the edge clock muxes on the left and right sides of the device. Figure 2-19 shows the selection muxes for these clocks.

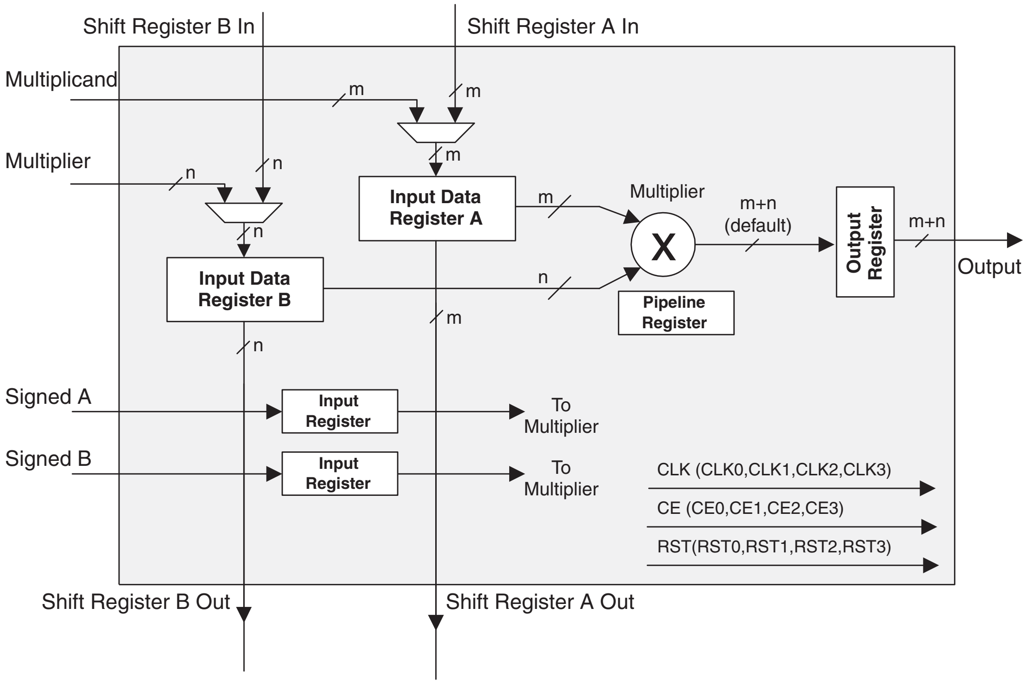
Figure 2-19. Edge Clock Mux Connections



MULT sysDSP Element

This multiplier element implements a multiply with no addition or accumulator nodes. The two operands, A and B, are multiplied and the result is available at the output. The user can enable the input/output and pipeline registers. Figure 2-23 shows the MULT sysDSP element.

Figure 2-23. MULT sysDSP Element



sets of single-ended input buffers (both ratioed and referenced). One of the referenced input buffers can also be configured as a differential input.

The two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

3. **Left and Right (Banks 2, 3, 6 and 7) sysI/O Buffer Pairs (50% Differential and 100% Single-Ended Outputs)**
The sysI/O buffer pairs in the left and right banks of the device consist of two single-ended output drivers, two sets of single-ended input buffers (both ratioed and referenced) and one differential output driver. One of the referenced input buffers can also be configured as a differential input. In these banks the two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential I/O, and the comp (complementary) pad is associated with the negative side of the differential I/O.

   LVDS differential output drivers are available on 50% of the buffer pairs on the left and right banks.

4. **Bank 8 sysI/O Buffer Pairs (Single-Ended Outputs, Only on Shared Pins When Not Used by Configuration)**
The sysI/O buffers in Bank 8 consist of single-ended output drivers and single-ended input buffers (both ratioed and referenced). The referenced input buffer can also be configured as a differential input.

   The two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

In LatticeECP2 devices, only the I/Os on the bottom banks have programmable PCI clamps. In LatticeECP2M devices, the I/Os on the left and bottom banks have programmable PCI clamps.

Typical sysI/O I/O Behavior During Power-up

The internal power-on-reset (POR) signal is deactivated when V_{CC}, V_{CCIO8} and V_{CCAUX} have reached satisfactory levels. After the POR signal is deactivated, the FPGA core logic becomes active. It is the user’s responsibility to ensure that all other V_{CCIO} banks are active with valid input logic levels to properly control the output logic states of all the I/O banks that are critical to the application. For more information about controlling the output logic state with valid input logic levels during power-up in LatticeECP2/M devices, see the list of additional technical documentation at the end of this data sheet.

The V_{CC} and V_{CCAUX} supply the power to the FPGA core fabric, whereas the V_{CCIO} supplies power to the I/O buffers. In order to simplify system design while providing consistent and predictable I/O behavior, it is recommended that the I/O buffers be powered-up prior to the FPGA core fabric. V_{CCIO} supplies should be powered-up before or together with the V_{CC} and V_{CCAUX} supplies.

Prior to and throughout programming of the FPGA, the I/O of the device have a weak-pullup resistor to V_{CCIO} on the input buffer and the output buffer is tri-stated. A pullup to V_{CCIO} is present on the input until the user programs the input differently in the FPGA design. See the DC Electrical Characteristics table of this data sheet. The pullup value will be between 20-30K ohms based on the V_{CCIO} voltage supplied on the board. This pullup will also remain active if the design does not use a particular I/O.

Supported sysI/O Standards

The LatticeECP2/M sysI/O buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS, LVTTL and other standards. The buffers support the LVTTL, LVCMOS 1.2V, 1.5V, 1.8V, 2.5V and 3.3V standards. In the LVCMOS and LVTTL modes, the buffer has individual configuration options for drive strength, bus maintenance (weak pull-up, weak pull-down, or a bus-keeper latch) and open drain. Other single-ended standards supported include SSTL and HSTL. Differential standards supported include LVDS, MLVDS, BLVDS, LVPECL, RSDS, differential SSTL and differential HSTL. Tables 2-13 and 2-14 show the I/

sysI/O Single-Ended DC Electrical Characteristics

Input/Output Standard	V_{IL}		V_{IH}		V_{OL} Max. (V)	V_{OH} Min. (V)	I_{OL}[1] (mA)	I_{OH}[1] (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVCMOS 3.3	-0.3	0.8	2.0	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVTTL	-0.3	0.8	2.0	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 2.5	-0.3	0.7	1.7	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.8	-0.3	0.35 V_{CCIO}	0.65 V_{CCIO}	3.6	0.4	V_{CCIO} - 0.4	16, 12, 8, 4	-16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.5	-0.3	0.35 V_{CCIO}	0.65 V_{CCIO}	3.6	0.4	V_{CCIO} - 0.4	8, 4	-8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.2	-0.3	0.35 V_{CC}	0.65 V_{CC}	3.6	0.4	V_{CCIO} - 0.4	6, 2	-6, -2
					0.2	V_{CCIO} - 0.2	0.1	-0.1
PCI	-0.3	0.3 V_{CCIO}	0.5 V_{CCIO}	3.6	0.1 V_{CCIO}	0.9 V_{CCIO}	1.5	-0.5
SSTL3 Class I	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.7	V_{CCIO} - 1.1	8	-8
SSTL3 Class II	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.5	V_{CCIO} - 0.9	16	-16
SSTL2 Class I	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.54	V_{CCIO} - 0.62	7.6	-7.6
							12	-12
SSTL2 Class II	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.35	V_{CCIO} - 0.43	15.2	-15.2
							20	-20
SSTL18 Class I	-0.3	V_{REF} - 0.125	V_{REF} + 0.125	3.6	0.4	V_{CCIO} - 0.4	6.7	-6.7
SSTL18 Class II	-0.3	V_{REF} - 0.125	V_{REF} + 0.125	3.6	0.28	V_{CCIO} - 0.28	8	-8
							11	-11
HSTL Class I	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	4	-4
							8	-8
HSTL18 Class I	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	8	-8
							12	-12
HSTL18 Class II	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	16	-16

1. The average DC current drawn by I/Os between GND connections, or between the last GND in an I/O bank and the end of an I/O bank, as shown in the logic signal connections table shall not exceed n * 8mA, where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.

BLVDS

The LatticeECP2/M devices support the BLVDS standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel external resistor across the driver outputs. BLVDS is intended for use when multi-drop and bi-directional multi-point differential signaling is required. The scheme shown in Figure 3-2 is one possible solution for bi-directional multi-point differential signals.

Figure 3-2. BLVDS Multi-point Output Example

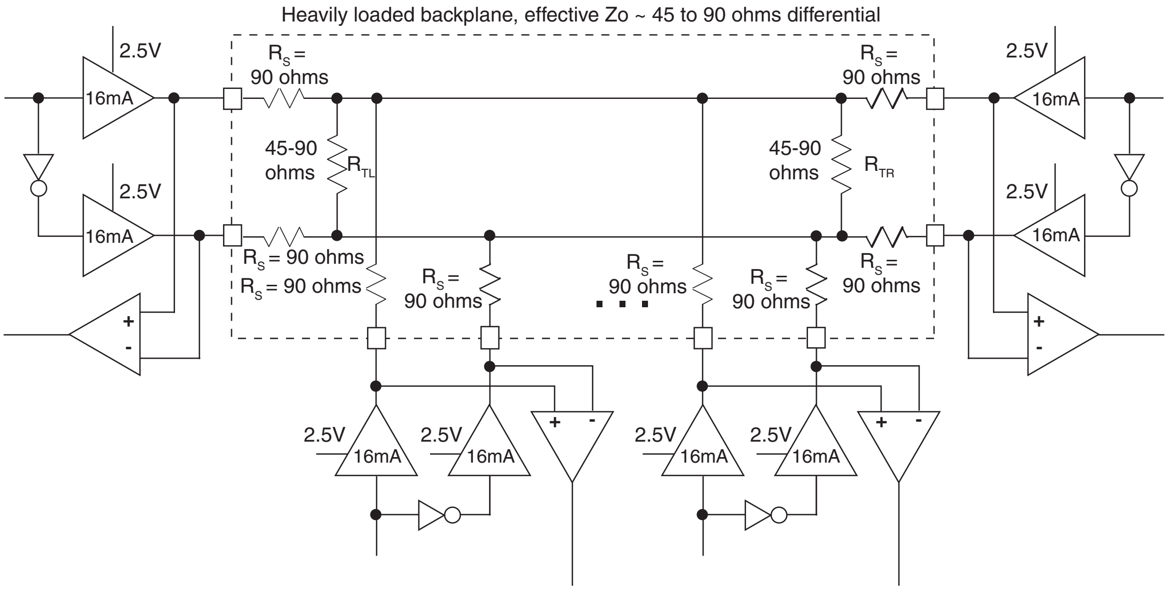


Table 3-3. BLVDS DC Conditions[1]

Over Recommended Operating Conditions

Parameter	Description	Typical		Units
		Zo = 45Ω	Zo = 90Ω	
V_{CCIO}	Output Driver Supply (+/- 5%)	2.50	2.50	V
Z_{OUT}	Driver Impedance	10.00	10.00	Ω
R_S	Driver Series Resistor (+/- 1%)	90.00	90.00	Ω
R_{TL}	Driver Parallel Resistor (+/- 1%)	45.00	90.00	Ω
R_{TR}	Receiver Termination (+/- 1%)	45.00	90.00	Ω
V_{OH}	Output High Voltage	1.38	1.48	V
V_{OL}	Output Low Voltage	1.12	1.02	V
V_{OD}	Output Differential Voltage	0.25	0.46	V
V_{CM}	Output Common Mode Voltage	1.25	1.25	V
I_{DC}	DC Output Current	11.24	10.20	mA

1. For input buffer, see LVDS table.

LatticeECP2/M External Switching Characteristics[9] (Continued)

Over Recommended Operating Conditions

Parameter	Description	Device	-7		-6		-5		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
t_{DIBSPI}	Data Invalid Before Clock (Transmit)	ECP2-20	—	280	—	280	—	280	ps
		ECP2-35	—	280	—	280	—	280	ps
		ECP2-50	—	280	—	280	—	280	ps
		ECP2-70	—	280	—	280	—	280	ps
		ECP2M20	—	230	—	230	—	230	ps
		ECP2M35	—	230	—	230	—	230	ps
		ECP2M50	—	230	—	230	—	230	ps
		ECP2M70	—	230	—	230	—	230	ps
		ECP2M100	—	230	—	230	—	230	ps
XGMII I/O Pin Parameters (312 Mbps)[5]									
$t_{SUXGMII}$	Data Setup Before Read Clock	ECP2/M	480	—	480	—	480	—	ps
t_{HXGMII}	Data Hold After Read Clock	ECP2/M	480	—	480	—	480	—	ps
$t_{DVBCKXGMII}$	Data Valid Before Clock	ECP2/M	960	—	960	—	960	—	ps
$t_{DVACKXGMII}$	Data Valid After Clock	ECP2/M	960	—	960	—	960	—	ps
Primary									
f_{MAX_PRI}[7]	Frequency for Primary Clock Tree	ECP2/M	—	420	—	357	—	311	MHz
t_{W_PRI}	Clock Pulse Width for Primary Clock	ECP2/M	0.95	—	1.19	—	2.00	—	ns
t_{SKEW_PRI}	Primary Clock Skew Within a Bank	ECP2/M	—	300	—	360	—	420	ps
Edge Clock									
f_{MAX_EDGE}[7]	Frequency for Edge Clock	ECP2/M	—	420	—	357	—	311	MHz
t_{W_EDGE}	Clock Pulse Width for Edge Clock	ECP2/M	0.95	—	1.19	—	2.00	—	ns
t_{SKEW_EDGE}	Edge Clock Skew Within an Edge of the Device	ECP2/M	—	300	—	360	—	420	ps

1. General timing numbers based on LVCMOS 2.5, 12mA, 0pf load.
2. DDR timing numbers based on SSTL25 for BGA packages only.
3. DDR2 timing numbers based on SSTL18 for BGA packages only.
4. SPI4.2 and SFI4 timing numbers based on LVDS25 for BGA packages only.
5. XGMII timing numbers based on HSTL class I. A corresponding left/right dedicated clock buffer is used when using the SPI4.2 interface to the left or right edge of the device. For SPI4.2 mode, the software tool will help in selecting the appropriate clock buffer.
6. IP will be used to support DDR and DDR2 memory data rates down to 95MHz. This approach uses a free-running clock and PFU register to sample the data instead of the hardwired DDR memory interface.
7. Using the LVDS I/O standard.
8. ECP2-6 and ECP2-12 do not support SPI4.2
9. The AC numbers do not apply to PCLK6 and PCLK7.
10. Applies to CLKOP only.
11. Please refer to TN1159, LatticeECP2/M Pin Assignment Recommendations for best performance.

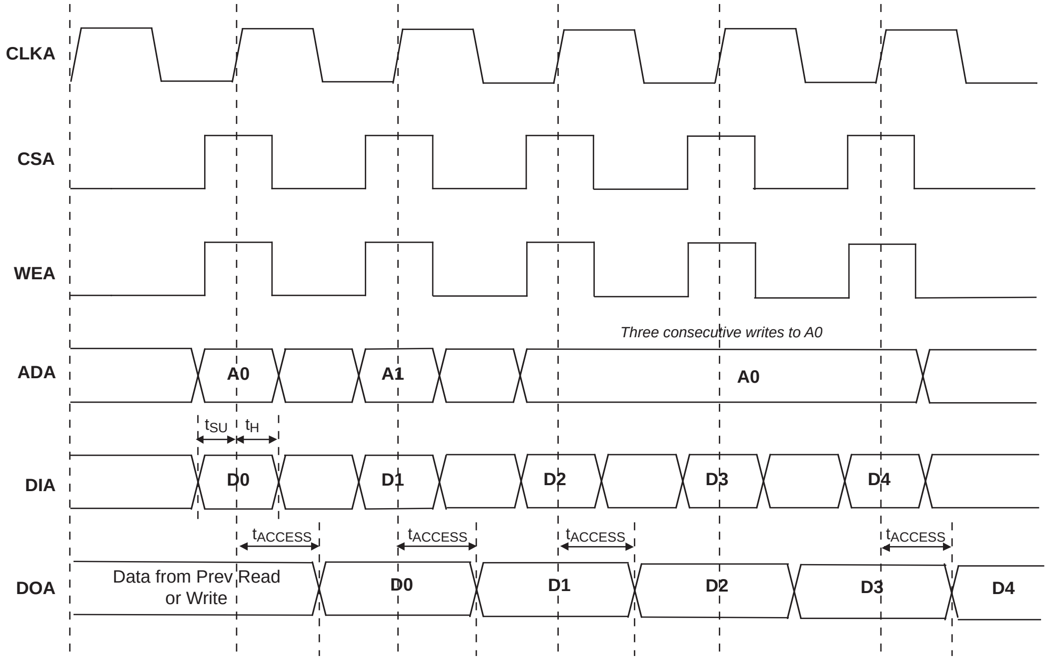
LatticeECP2/M Internal Switching Characteristics[1] (Continued)

Over Recommended Operating Conditions

Parameter	Description	-7		-6		-5		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t_{HWREN_EBR}	Hold Write/Read Enable to PFU Memory	0.139	—	0.156	—	0.173	—	ns
t_{SUCE_EBR}	Clock Enable Setup Time to EBR Output Register	0.123	—	0.134	—	0.145	—	ns
t_{HCE_EBR}	Clock Enable Hold Time to EBR Output Register	-0.081	—	-0.090	—	-0.100	—	ns
t_{RSTO_EBR}	Reset To Output Delay Time from EBR Output Register	—	1.03	—	1.15	—	1.26	ns
t_{SUBE_EBR}	Byte Enable Set-Up Time to EBR Output Register	-0.115	—	-0.130	—	-0.145	—	ns
t_{HBE_EBR}	Byte Enable Hold Time to EBR Output Register	0.138	—	0.155	—	0.172	—	ns
GPLL Parameters								
t_{RSTREC_GPLL}	Reset Recovery to Rising Clock	1.00	—	1.00	—	1.00	—	ns
SPLL Parameters								
t_{RSTREC_SPLL}	Reset Recovery to Rising Clock	1.00	—	1.00	—	1.00	—	ns
DSP Block Timing[2,3]								
t_{SUI_DSP}	Input Register Setup Time	0.12	—	0.13	—	0.14	—	ns
t_{HI_DSP}	Input Register Hold Time	0.02	—	-0.01	—	-0.03	—	ns
t_{SUP_DSP}	Pipeline Register Setup Time	2.18	—	2.42	—	2.66	—	ns
t_{tHP_DSP}	Pipeline Register Hold Time	-0.68	—	-0.77	—	-0.86	—	ns
t_{SUO_DSP}	Output Register Setup Time	4.26	—	4.71	—	5.16	—	ns
t_{HO_DSP}	Output Register Hold Time	-1.25	—	-1.40	—	-1.54	—	ns
t_{COI_DSP}	Input Register Clock to Output Time	—	3.92	—	4.30	—	4.68	ns
t_{COP_DSP}	Pipeline Register Clock to Output Time	—	1.87	—	1.98	—	2.08	ns
t_{COO_DSP}	Output Register Clock to Output Time	—	0.50	—	0.52	—	0.55	ns
$t_{SUADDSUB}$	AddSub Input Register Setup Time	-0.24	—	-0.26	—	-0.28	—	ns
$t_{HADDSUB}$	AddSub Input Register Hold Time	0.27	—	0.29	—	0.32	—	ns

1. Internal parameters are characterized but not tested on every device.
2. These parameters apply to LatticeECP devices only.
3. DSP Block is configured in Multiply Add/Sub 18x18 Mode.

Figure 3-11. Write Through (SP Read/Write on Port A, Input Registers Only)



Note: Input data and address are registered at the positive edge of the clock and output data appears after the positive edge of the clock.

sysCLOCK GPLL Timing

Over Recommended Operating Conditions

Parameter	Description	Conditions	Min.	Typ.	Max.	Units
f_{IN}	Input Clock Frequency (CLKI, CLKFB)	Without external capacitor	20	—	420	MHz
		With external capacitor[5, 6]	2	—	420	MHz
f_{OUT}	Output Clock Frequency (CLKOP, CLKOS)	Without external capacitor	20	—	420	MHz
		With external capacitor[5]	5	—	50	MHz
f_{OUT2}	K-Divider Output Frequency (CLKOK)	Without external capacitor	0.156	—	210	MHz
		With external capacitor[5]	0.039	—	25	MHz
f_{VCO}	PLL VCO Frequency		640	—	1280	MHz
f_{PFD}	Phase Detector Input Frequency	Without external capacitor	20	—	420	MHz
		With external capacitor[5, 6]	2	—	50	MHz
AC Characteristics						
t_{DT}	Output Clock Duty Cycle	Default duty cycle selected[3]	45	50	55	%
t_{PH}[4]	Output Phase Accuracy		—	—	±0.05	UI
t_{OPJIT}[1]	Output Clock Period Jitter	$f_{OUT} \geq 100$ MHz	—	—	±125	ps
		$50 \leq f_{OUT} < 100$ MHz	—		0.025	UIPP
		$f_{OUT} < 50$ MHz	—	—	0.04	UIPP
t_{SK}	Input Clock to Output Clock Skew	N/M = integer	—	—	±250	ps
t_W	Output Clock Pulse Width	At 90% or 10%	1	—	—	ns
t_{LOCK}[2]	PLL Lock-in Time	Without external capacitor	—	—	150	µs
		With external capacitor[5]	—	—	500	µs
t_{PA}	Programmable Delay Unit		85	130	360	ps
t_{IPJIT}	Input Clock Period Jitter		—	—	±200	ps
t_{FBKDLY}	External Feedback Delay		—	—	10	ns
t_{HI}	Input Clock High Time	90% to 90%	0.5	—	—	ns
t_{LO}	Input Clock Low Time	10% to 10%	0.5	—	—	ns
t_{RST}	RST Pulse Width (RESETM/RESETK)		15	—	—	ns
	Reset Signal Pulse Width (CNTRST)	Without external capacitor	500	—	—	ns
		With external capacitor[5]	20	—	—	µs

1. Jitter sample is taken over 10,000 samples of the primary PLL output with clean reference clock and no additional I/O pins toggling.
2. Output clock is valid after t_{LOCK} for PLL reset and dynamic delay adjustment.
3. Using LVDS output buffers.
4. Relative to CLKOP.
5. Value of external capacitor: 5.6 nF ±20%, NPO dielectric, ceramic chip capacitor, 1206 or smaller package, connected to PLLCAP pin.
6. f_{OUT} (max) = f_{IN} * 10 for $f_{IN} < 5$MHz.

LatticeECP2M Pin Information Summary, LFE2M50, LFE2M70 and LFE2M100 (Cont.)

Pin Type		LFE2M50			LFE2M70		LFE2M100	
		484 fpBGA	672 fpBGA	900 fpBGA	900 fpBGA	1152 fpBGA	900 fpBGA	1152 fpBGA
Available DDR-Interfaces per I/O Bank[1]	Bank0	0	0	0	0	0	0	0
	Bank1	0	0	0	0	0	0	0
	Bank2	2	2	2	4	4	4	4
	Bank3	2	1	1	3	4	3	5
	Bank4	3	1	3	3	3	3	3
	Bank5	2	3	3	2	3	2	3
	Bank6	1	2	2	3	4	3	5
	Bank7	3	3	3	4	4	4	5
	Bank8	0	0	0	0	0	0	0
PCI Capable I/Os per Bank	Bank0	0	0	0	0	0	0	0
	Bank1	0	0	0	0	0	0	0
	Bank2	0	0	0	0	72	0	80
	Bank3	0	0	0	0	64	0	80
	Bank4	50	24	48	48	40	48	44
	Bank5	60	60	50	40	40	40	46
	Bank6	52	54	60	62	66	62	82
	Bank7	60	60	68	70	74	70	90
	Bank8	0	0	0	0	0	0	0

1. Minimum requirement to implement a fully functional 8-bit wide DDR bus. Available DDR interface consists of at least 12 I/Os (1 DQS + 1 DQSB + 8 DQs + 1 DM + Bank VREF1).

Available Device Resources by Package, LatticeECP2

Resource	Device	256 fpBGA	484 fpBGA	672 fpBGA	900 fpBGA
PLL/DLL	ECP2-6	4	—	—	—
	ECP2-12	4	4	—	—
	ECP2-20	4	4	4	—
	ECP2-35	—	4	4	—
	ECP2-50	—	6	6	—
	ECP2-70	—	—	8	8

Available Device Resources by Package, LatticeECP2M

Resource	Device	256 fpBGA	484 fpBGA	672 fpBGA	900 fpBGA	1152 fpBGA
PLL/DLL	ECP2M20	10	10	—	—	—
	ECP2M35	10	10	10	—	—
	ECP2M50	—	10	10	10	—
	ECP2M70	—	—	—	10	10
	ECP2M100	—	—	—	10	10

LatticeECP2M Power Supply and NC

Signal	256 fpBGA	484 fpBGA
V_{CC}	G7, G9, H7, J10, K10, K8	J10, J11, J12, J13, K14, K9, L14, L9, M14, M9, N14, N9, P10, P11, P12, P13
V_{CCIO0}	E7	B5, B9, E7, H9
V_{CCIO1}	E10	D13, E16, H14
V_{CCIO2}	E14, G12	E21, G18, J15, K19
V_{CCIO3}	K12, M14	N19, P15, T18, V21
V_{CCIO4}	M10, P12	AA18, R14, V16, W13
V_{CCIO5}	M7, P5	AA5, R9, V7, W10
V_{CCIO6}	K5, M3	N4, P8, T5, V2
V_{CCIO7}	E3, G5	E2, G5, J8, K4
V_{CCIO8}	T15	AA22, U19
V_{CCJ}	K7	W4
V_{CCAUX}	G8, H10, J7, K9	H11, H12, L15, L8, M15, M8, R11, R12
V_{CCPLL}	G10	R8, H15, H8, R15
SERDES Power[3]	C15, B15, C12, A12, C11, C10, C14, C13, B9, C9, C5, C4, C8, C7, A6, C6, B3, C3	C22, B22, C19, A19, C18, C17, C21, C20, B16, C16, C12, C11, C15, C14, A13, C13, B10, C10
GND[1]	A1, A15, A16, A3, A9, B12, B6, E15, E2, H14, H8, H9, J3, J8, J9, M15, M2, P9, R12, R5, T1, T16	A1, A10, A16, A22, AA19, AA4, AB1, AB22, B13, B19, B4, D16, D2, D21, D7, G19, G4, H10, H13, J14, J9, K10, K11, K12, K13, K15, K20, K3, K8, L10, L11, L12, L13, M10, M11, M12, M13, N10, N11, N12, N13, N15, N20, N3, N8, P14, P9, R10, R13, T19, T4, W16, W2, W21, W7, Y10, Y13
NC[2]	D10, D11, D12, D13, D14, D4, D5, D6, D7, E11, E6, E8, E9, F10, F7, F8, F9	**LFE2M20:** D14, D15, E14, E15, F13, F14, F15, G12, G13, G14, G15 **LFE2M35:** D14, D15, E14, E15, F13, F14, F15, G12, G13, G14, G15, U6 **LFE2M50:** Y15, W15, AB20, AB21, AA20, AB19, AB18, Y22, Y21, Y17, Y18, Y16, W17, Y19, Y20, W19, W18, V17, V18, D15, G14, G15, D14, E15, E14, F15, F14, F13, G12, G13

1. All grounds must be electrically connected at the board level. For fpBGA packages, the total number of GND balls is less than the actual number of GND logic connections from the die to the common package GND plane.
2. NC pins should not be connected to any active signals, VCC or GND.
3. For package migration across device densities, the designer must comprehend the package pin requirements for the SERDES blocks. Specifically, the SERDES power pins of the largest density device must be accounted to accommodate migration to other smaller devices using the same package. Please refer to TN1160, LatticeECP2/M Density Migration for more details.

LFE2-6E/SE and LFE2-12E/SE Logic Signal Connections: 256 fpBGA (Cont.)

LFE2-6E/SE					LFE2-12E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
-	-	-			GNDIO1	1		
-	-	-			VCCIO	1		
D10	PT19B	1		C	PT37B	1		C
C10	PT19A	1		T	PT37A	1		T
GND	GNDIO1	-			GNDIO1	-		
B10	PT18B	1		C	PT36B	1		C
A9	PT17B	1		C	PT35B	1		C
A10	PT18A	1		T	PT36A	1		T
B9	PT17A	1		T	PT35A	1		T
VCCIO	VCCIO1	1			VCCIO1	1		
A8	PT16B	1		C	PT34B	1		C
D9	PT15B	1		C	PT33B	1		C
B8	PT16A	1		T	PT34A	1		T
C9	PT15A	1		T	PT33A	1		T
GND	GNDIO1	-			GNDIO1	-		
B7	PT14B	1		C	PT32B	1		C
E9	PT13B	1		C	PT31B	1		C
A7	PT14A	1		T	PT32A	1		T
D8	PT13A	1		T	PT31A	1		T
VCCIO	VCCIO1	1			VCCIO1	1		
A6	PT12B	1	PCLKC1_0	C	PT30B	1	PCLKC1_0	C
B6	PT12A	1	PCLKT1_0	T	PT30A	1	PCLKT1_0	T
E6	XRES	-			XRES	1		
F8	PT10B	0	PCLKC0_0	C	PT28B	0	PCLKC0_0	C
GND	GNDIO0	-			GNDIO0	-		
E8	PT10A	0	PCLKT0_0	T	PT28A	0	PCLKT0_0	T
A5	PT9B	0		C	PT27B	0		C
A3	PT8B	0		C	PT26B	0		C
A4	PT9A	0		T	PT27A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
B3	PT8A	0		T	PT26A	0		T
A2	PT7B	0		C	PT25B	0		C
C7	PT6B	0		C	PT24B	0		C
B2	PT7A	0		T	PT25A	0		T
D7	PT6A	0		T	PT24A	0		T
D6	PT5B	0		C	PT23B	0		C
GND	GNDIO0	-			GNDIO0	-		
F7	PT4B	0		C	PT22B	0		C
C6	PT5A	0		T	PT23A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
F6	PT4A	0		T	PT22A	0		T
C4	PT3B	0		C	PT21B	0		C
B4	PT3A	0		T	PT21A	0		T
-	-	-			GNDIO0	0		
-	-	-			VCCIO	0		

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

	LFE2-20E/20SE				LFE2-35E/35SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
L2	NC	-			NC	-		
L1	NC	-			NC	-		
VCCIO	VCCIO7	7			VCCIO7	7		
M2	NC	-			NC	-		
M1	NC	-			NC	-		
N2	NC	-			NC	-		
GND	GNDIO7	-			GNDIO7	-		
M8	VCC	-			NC	-		
VCCIO	VCCIO7	7			VCCIO7	7		
GND	GNDIO7	-			GNDIO7	-		
N1	PL12A	7	LDQ16		PL18A	7	LDQ22	
L8	PL13A	7	LDQ16	T	PL19A	7	LDQ22	T
K8	PL13B	7	LDQ16	C	PL19B	7	LDQ22	C
VCCIO	VCCIO7	7			VCCIO7	7		
L6	PL14A	7	LDQ16	T (LVDS)*	PL20A	7	LDQ22	T (LVDS)*
K5	PL14B	7	LDQ16	C (LVDS)*	PL20B	7	LDQ22	C (LVDS)*
L7	PL15A	7	LDQ16	T	PL21A	7	LDQ22	T
L5	PL15B	7	LDQ16	C	PL21B	7	LDQ22	C
GND	GNDIO7	-			GNDIO7	-		
P1	PL16A	7	LDQS16	T (LVDS)*	PL22A	7	LDQS22	T (LVDS)*
P2	PL16B	7	LDQ16	C (LVDS)*	PL22B	7	LDQ22	C (LVDS)*
M6	PL17A	7	LDQ16	T	PL23A	7	LDQ22	T
VCCIO	VCCIO7	7			VCCIO7	7		
N8	PL17B	7	LDQ16	C	PL23B	7	LDQ22	C
R1	PL18A	7	LDQ16	T (LVDS)*	PL24A	7	LDQ22	T (LVDS)*
R2	PL18B	7	LDQ16	C (LVDS)*	PL24B	7	LDQ22	C (LVDS)*
M7	PL19A	7	PCLKT7_0/LDQ16	T	PL25A	7	PCLKT7_0/LDQ22	T
GND	GNDIO7	-			GNDIO7	-		
N9	PL19B	7	PCLKC7_0/LDQ16	C	PL25B	7	PCLKC7_0/LDQ22	C
M4	PL21A	6	PCLKT6_0/LDQ25	T (LVDS)*	PL27A	6	PCLKT6_0/LDQ31	T (LVDS)*
M5	PL21B	6	PCLKC6_0/LDQ25	C (LVDS)*	PL27B	6	PCLKC6_0/LDQ31	C (LVDS)*
N7	PL22A	6	VREF2_6/LDQ25	T	PL28A	6	VREF2_6/LDQ31	T
P9	PL22B	6	VREF1_6/LDQ25	C	PL28B	6	VREF1_6/LDQ31	C
N3	PL23A	6	LDQ25	T (LVDS)*	PL29A	6	LDQ31	T (LVDS)*
VCCIO	VCCIO6	6			VCCIO6	6		
N4	PL23B	6	LDQ25	C (LVDS)*	PL29B	6	LDQ31	C (LVDS)*
N5	PL24A	6	LDQ25	T	PL30A	6	LDQ31	T
P7	PL24B	6	LDQ25	C	PL30B	6	LDQ31	C
T1	NC	-			PL31A	6	LDQS31	T (LVDS)*
GND	GNDIO6	-			GNDIO6	-		
T2	NC	-			PL31B	6	LDQ31	C (LVDS)*
P8	NC	-			PL32A	6	LDQ31	T
P6	NC	-			PL32B	6	LDQ31	C
VCCIO	VCCIO6	6			VCCIO6	6		
P5	NC	-			PL33A	6	LDQ31	T (LVDS)*
P4	NC	-			PL33B	6	LDQ31	C (LVDS)*

LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-50E/SE					LFE2-70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
D4	PT7B	0		C	PT7B	0		C
D3	PT7A	0		T	PT7A	0		T
C2	PT6B	0		C	PT6B	0		C
C1	PT6A	0		T	PT6A	0		T
G8	PT5B	0		C	PT5B	0		C
GND	GNDIO0	-			GNDIO0	-		
G7	PT5A	0		T	PT5A	0		T
E7	PT4B	0		C	PT4B	0		C
VCCIO	VCCIO0	0			VCCIO0	0		
F7	PT4A	0		T	PT4A	0		T
E6	PT3B	0		C	PT3B	0		C
E5	PT3A	0		T	PT3A	0		T
G6	PT2B	0	VREF2_0	C	PT2B	0	VREF2_0	C
G5	PT2A	0	VREF1_0	T	PT2A	0	VREF1_0	T
L12	VCC	-			VCC	-		
L13	VCC	-			VCC	-		
L14	VCC	-			VCC	-		
L15	VCC	-			VCC	-		
M11	VCC	-			VCC	-		
M12	VCC	-			VCC	-		
M15	VCC	-			VCC	-		
M16	VCC	-			VCC	-		
N11	VCC	-			VCC	-		
N16	VCC	-			VCC	-		
P11	VCC	-			VCC	-		
P16	VCC	-			VCC	-		
R11	VCC	-			VCC	-		
R12	VCC	-			VCC	-		
R15	VCC	-			VCC	-		
R16	VCC	-			VCC	-		
T12	VCC	-			VCC	-		
T13	VCC	-			VCC	-		
T14	VCC	-			VCC	-		
T15	VCC	-			VCC	-		
D11	VCCIO0	0			VCCIO0	0		
D6	VCCIO0	0			VCCIO0	0		
G9	VCCIO0	0			VCCIO0	0		
K12	VCCIO0	0			VCCIO0	0		
J12	VCCIO0	0			VCCIO0	0		
D16	VCCIO1	1			VCCIO1	1		
D21	VCCIO1	1			VCCIO1	1		
G18	VCCIO1	1			VCCIO1	1		
J15	VCCIO1	1			VCCIO1	1		
K15	VCCIO1	1			VCCIO1	1		
F23	VCCIO2	2			VCCIO2	2		
J20	VCCIO2	2			VCCIO2	2		

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
K28	PR25A	2	RDQ29	T (LVDS)*
J24	PR24B	2	RDQ21	C
J26	PR24A	2	RDQ21	T
GND	GNDIO2	-		
K29	PR23B	2	RDQ21	C (LVDS)*
K30	PR23A	2	RDQ21	T (LVDS)*
J23	PR22B	2	RDQ21	C
J25	PR22A	2	RDQ21	T
VCCIO	VCCIO2	99		
J27	PR21B	2	RDQ21	C (LVDS)*
J28	PR21A	2	RDQS21	T (LVDS)*
H26	PR20B	2	RDQ21	C
GND	GNDIO2	-		
H24	PR20A	2	RDQ21	T
J29	PR19B	2	RDQ21	C (LVDS)*
J30	PR19A	2	RDQ21	T (LVDS)*
H25	PR18B	2	RDQ21	C
VCCIO	VCCIO2	2		
H23	PR18A	2	RDQ21	T
G27	PR15B	2	RUM1_SPLLC_FB_A/RDQ12	C
GND	GNDIO2	-		
H27	PR15A	2	RUM1_SPLLT_FB_A/RDQ12	T
G29	PR14B	2	RUM1_SPLLC_IN_A/RDQ12	C (LVDS)*
G28	PR14A	2	RUM1_SPLLT_IN_A/RDQ12	T (LVDS)*
VCCIO	VCCIO2	2		
GND	GNDIO2	-		
G26	PR6B	2		C (LVDS)*
G25	PR6A	2		T (LVDS)*
G30	PR5B	2		C
F30	PR5A	2		T
VCCIO	VCCIO2	2		
F26	PR4B	2		C (LVDS)*
F27	PR4A	2		T (LVDS)*
F29	PR3B	2		C
GND	GNDIO2	-		
F28	PR3A	2		T
H29	PR2B	2	VREF2_2	C (LVDS)*
H30	PR2A	2	VREF1_2	T (LVDS)*
VCCIO	VCCIO2	2		
B26	PT100B	1	VREF2_1	C
A26	PT100A	1	VREF1_1	T
GND	GNDIO1	-		
C25	PT99B	1		C

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
C17	PT58B	1		C
A18	PT58A	1		T
VCCIO	VCCIO1	1		
H16	PT57B	1	PCLKC1_0	C
F16	PT57A	1	PCLKT1_0	T
K16	XRES	1		
E16	PT55B	0	PCLKC0_0	C
GND	GNDIO0	-		
G16	PT55A	0	PCLKT0_0	T
B17	PT54B	0		C
A17	PT54A	0		T
J15	PT53B	0		C
VCCIO	VCCIO0	0		
J16	PT53A	0		T
C16	PT52B	0		C
D16	PT52A	0		T
F15	PT51B	0		C
H15	PT51A	0		T
E15	PT50B	0		C
GND	GNDIO0	-		
G15	PT50A	0		T
C15	PT49B	0		C
VCCIO	VCCIO0	0		
D15	PT49A	0		T
B16	PT48B	0		C
A16	PT48A	0		T
E14	PT47B	0		C
G14	PT47A	0		T
B15	PT46B	0		C
A15	PT46A	0		T
GND	GNDIO0	-		
H14	PT45B	0		C
F14	PT45A	0		T
D14	PT44B	0		C
C14	PT44A	0		T
VCCIO	VCCIO0	0		
G13	PT43B	0		C
E13	PT43A	0		T
B14	PT42B	0		C
A14	PT42A	0		T
GND	GNDIO0	-		
H13	PT41B	0		C
F13	PT41A	0		T

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA

LFE2M50E/SE					LFE2M70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
D2	PL9A	7	VREF2_7/LDQ6	T	PL9A	7	VREF2_7	T
D3	PL9B	7	VREF1_7/LDQ6	C	PL9B	7	VREF1_7	C
GNDIO	GNDIO7	-			GNDIO7	-		
J8	PL11A	7	LUM0_SPLLT_IN_A	T (LVDS)*	PL11A	7	LUM0_SPLLT_IN_A/LDQ15	T (LVDS)*
H7	PL11B	7	LUM0_SPLLC_IN_A	C (LVDS)*	PL11B	7	LUM0_SPLLC_IN_A/LDQ15	C (LVDS)*
E3	PL12A	7	LUM0_SPLLT_FB_A	T	PL12A	7	LUM0_SPLLT_FB_A/LDQ15	T
E4	PL12B	7	LUM0_SPLLC_FB_A	C	PL12B	7	LUM0_SPLLC_FB_A/LDQ15	C
GNDIO	GNDIO7	-			-	-		
G6	PL13A	7		T (LVDS)*	PL13A	7	LDQ15	T (LVDS)*
F5	PL13B	7		C (LVDS)*	PL13B	7	LDQ15	C (LVDS)*
E2	PL14A	7		T	PL14A	7	LDQ15	T
D1	PL14B	7		C	PL14B	7	LDQ15	C
-	-	-			GNDIO7	-		
G5	NC	-			PL15A	7	LDQS15	T (LVDS)*
G4	NC	-			PL15B	7	LDQ15	C (LVDS)*
K7	NC	-			PL16A	7	LDQ15	T
K8	NC	-			PL16B	7	LDQ15	C
E1	NC	-			PL17A	7	LDQ15	T (LVDS)*
F2	NC	-			PL17B	7	LDQ15	C (LVDS)*
F1	NC	-			PL18A	7	LDQ15	T
-	-	-			GNDIO7	-		
G3	NC	-			PL18B	7	LDQ15	C
H5	PL15A	7		T (LVDS)*	PL21A	7		T (LVDS)*
H4	PL15B	7		C (LVDS)*	PL21B	7		C (LVDS)*
J5	PL16A	7		T	PL22A	7		T
J4	PL16B	7		C	PL22B	7		C
GNDIO	GNDIO7	-			GNDIO7	-		
G2	NC	-			PL24A	7	LDQ28	T (LVDS)*
G1	NC	-			PL24B	7	LDQ28	C (LVDS)*
L9	NC	-			PL25A	7	LDQ28	T
L7	NC	-			PL25B	7	LDQ28	C
K6	NC	-			PL26A	7	LDQ28	T (LVDS)*
K5	NC	-			PL26B	7	LDQ28	C (LVDS)*
L8	NC	-			PL27A	7	LDQ28	T
L6	NC	-			PL27B	7	LDQ28	C
-	-	-			GNDIO7	-		
H3	PL18A	7		T (LVDS)*	PL28A	7	LDQS28	T (LVDS)*
H2	PL18B	7		C (LVDS)*	PL28B	7	LDQ28	C (LVDS)*
N8	PL19A	7		T	PL29A	7	LDQ28	T
M9	PL19B	7		C	PL29B	7	LDQ28	C
J3	PL20A	7		T (LVDS)*	PL30A	7	LDQ28	T (LVDS)*
VCCIO	VCCIO7	7			-	-		
J2	PL20B	7		C (LVDS)*	PL30B	7	LDQ28	C (LVDS)*
H1	PL21A	7		T	PL31A	7	LDQ28	T
GNDIO	GNDIO7	-			GNDIO7	-		
J1	PL21B	7		C	PL31B	7	LDQ28	C
-	-	-			-	-		
-	-	-			-	-		

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
U7	PL60A	6	VREF2_6/LDQ63	T
T8	PL60B	6	VREF1_6/LDQ63	C
R3	PL61A	6	LDQ63	T (LVDS)*
VCCIO	VCCIO6	6		
R2	PL61B	6	LDQ63	C (LVDS)*
R1	PL62A	6	LDQ63	T
T1	PL62B	6	LDQ63	C
GNDIO	GNDIO6	-		
VCCIO	VCCIO6	6		
T3	PL65A	6	LLM4_SPLLT_IN_A/LDQ63	T (LVDS)*
T2	PL65B	6	LLM4_SPLLC_IN_A/LDQ63	C (LVDS)*
U9	PL66A	6	LLM4_SPLLT_FB_A/LDQ63	T
U8	PL66B	6	LLM4_SPLLC_FB_A/LDQ63	C
GNDIO	GNDIO6	-		
U5	PL68A	6	LDQ72	T (LVDS)*
U4	PL68B	6	LDQ72	C (LVDS)*
V9	PL69A	6	LDQ72	T
V7	PL69B	6	LDQ72	C
VCCIO	VCCIO6	6		
U3	PL70A	6	LDQ72	T (LVDS)*
U2	PL70B	6	LDQ72	C (LVDS)*
V8	PL71A	6	LDQ72	T
U6	PL71B	6	LDQ72	C
GNDIO	GNDIO6	-		
U1	PL72A	6	LDQS72	T (LVDS)*
V2	PL72B	6	LDQ72	C (LVDS)*
V5	PL73A	6	LDQ72	T
VCCIO	VCCIO6	6		
V6	PL73B	6	LDQ72	C
V1	PL74A	6	LDQ72	T (LVDS)*
W1	PL74B	6	LDQ72	C (LVDS)*
W5	PL75A	6	LDQ72	T
GNDIO	GNDIO6	-		
W6	PL75B	6	LDQ72	C
W3	PL77A	6	LDQ81	T (LVDS)*
W4	PL77B	6	LDQ81	C (LVDS)*
W2	PL78A	6	LDQ81	T
Y4	PL78B	6	LDQ81	C
Y1	PL79A	6	LDQ81	T (LVDS)*
VCCIO	VCCIO6	6		
Y2	PL79B	6	LDQ81	C (LVDS)*
Y5	PL80A	6	LDQ81	T
Y6	PL80B	6	LDQ81	C